

Amendments to the Claims

Claims 1-7 (Canceled)

Claim 8 (Currently Amended) A circuit electrode bonding apparatus comprising:

- a measuring section for measuring a size of a bonding portion of a circuit electrode;
- a comparing section for comparing the measured size of the bonding portion with a designed size of the bonding portion;
- a size determination section for determining a processing size of ~~the~~ a bonding material based on a comparison result of the comparing section;
- a processing section for processing the bonding material to the processing size;
- a mounting section for mounting the processed bonding material over the bonding portion;
- and
- a location determination section for determining a location of the bonding portion for mounting the processed bonding material based on the comparison result.

Claims 9-12 (Canceled)

Claim 13 (New) A circuit electrode bonding apparatus according to claim 8, wherein the measuring section measures the size of the bonding portion of the circuit electrode at a bonding temperature at which the processed bonding material is to be bound to the bounding portion.

Claim 14 (New) A circuit electrode bonding apparatus according to claim 13, wherein the comparing section compares the measured size of the bonding portion at the bonding temperature with the designed size of the bonding portion at the bonding temperature and generates a ratio of the measured size and the designed size as the comparison result.

Claim 15 (New) A circuit electrode bonding apparatus according to claim 14, wherein the size determination section determines the processing size of the bonding material at a processing temperature at which the processing section processes the bonding material by multiplying the comparison result, a designed size of the bonding material at the bonding temperature, and a thermal expansion coefficient.

Claim 16 (New) A circuit electrode bonding apparatus according to claim 14, wherein the bonding temperature is higher than the processing temperature.

Claim 17 (New) A circuit electrode bonding apparatus according to claim 14, wherein the bonding temperature is approximately 80°C and the processing temperature is approximately 25°C.

Claim 18 (New) A circuit electrode bonding apparatus according to claim 8, wherein the location determination section determines the location of the bonding portion for bonding the processed bonding material by multiplying a designed size of a pitch of the bonding portion by the comparison result.

Claim 19 (New) A circuit electrode bonding apparatus according to claim 15, wherein the location determination section determines the location of the bonding portion for bonding the processed bonding material by multiplying a designed size of a pitch of the bonding portion by the comparison result.

Claim 20 (New) A circuit electrode bonding apparatus according to claim 8, wherein the bonding material is an anisotropic conductive film.

Claim 21 (New) A circuit electrode bonding apparatus according to claim 20, wherein the processing section processes the anisotropic conductive film to the processing size by cutting the anisotropic conductive film.